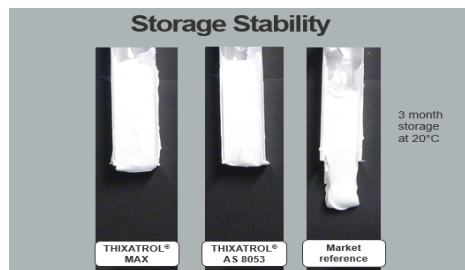


Rheology Modifiers for High Performance Adhesives and Sealant Systems

THIXATROL® Organic Thixotropes from Elementis, an industry leader in innovation and sustainability, greatly improves the formulation of adhesives and sealants for high performance applications. The low temperature activation enables up to 50% increased manufacturing efficiency. The high share of bio-based raw materials creates products to meet high sustainability demands. Our application labs and technical experts are at your service to support you in order to maximize the benefits in your formulation.

THIXATROL® rheology modifiers for adhesives and sealants provide the following system benefits versus traditional rheological additives (fumed silica, micronized waxes, etc.)

- Lower activation temperature allows up to 50% higher throughput, energy savings and improved production process
- Enhanced extrudability, no thread formation
- Up to 50% higher efficiency resulting in excellent slump/ sag resistance
- Improved viscosity stability on storage
- Easier (much less dust) incorporation and safer handling versus fumed silica
- Compared to fumed silica, 20 times higher density allowing less volume in transport and storage space
- THIXATROL® AS 8053, PM 8054 and PM 8056 are labeling- free and based on renewable raw material sources



Performance system for high performance adhesives and sealants

Product Name	Product Type	Composition	Description
THIXATROL® AS 8053	Rheology Modifier	Amide Based Organic Thixotrope in Powder Form	- For solvent-free, high solid and solvent-borne systems, e.g. MS polymer sealants - Activation temperature 40 – 60°C
THIXATROL® PM 8054	Rheology Modifier		- For solvent-free, high solid and solventborne systems, esp. low polarity systems and SPUR sealants - Activation temperature 50 – 70°C
THIXATROL® PM 8056	Rheology Modifier		- For solvent-free, high solid and solventborne systems, esp. high polarity systems and SPUR and MS polymer sealants - Activation temperature 40 – 70°C
THIXATROL® MAX	Rheology Modifier		- For solvent-free, solventborne and high solid systems - Activation temperature 65 – 85°C depending on polarity - High temperature activation for removal of moisture